



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-03-07
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH8R06DIRG	HZUR*R53S11G	A	SH1A	2017-03-07
Amount	UoM	Unit type	ST ECOPACK Grade	
2170.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte, annealed	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10,15,5,4,5	2	Through-hole	
Comment	Package: DO 220 AB ISOL.			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-12th January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HZUR*RS3511G						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	7.326	mg	supplier	die	Silicon (Si)	7440-21-3		7.191	mg	981572	3314	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.04	mg	5460	18	
				supplier	polymer die coating	Propimide	proprietary		0.051	mg	6962	24	
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	273	1	
				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	956	3	
Leadframe	Copper & its alloys	1536.59	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.035	mg	4778	16	
				supplier	alloy	Copper (Cu)	7440-50-8		1531.293	mg	996553	705665	
				supplier	alloy	Iron (Fe)	7439-89-6		0.705	mg	459	325	
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.288	mg	839	594	
				supplier	metallization	Nickel (Ni)	7440-02-0		3.304	mg	2150	1523	
Soft solder	Solder	2.593	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.398	mg	924798	1105	
				supplier	solder	Silver (Ag)	7440-22-4		0.13	mg	50135	60	
				supplier	solder	Tin (Sn)	7440-31-5		0.065	mg	25067	30	
Soft solder -2	Solder	2.437	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.071	mg	849815	954	
				supplier	solder	Antimony (Sb)	7440-36-0		0.244	mg	100123	112	
				supplier	solder	Tin (Sn)	7440-31-5		0.122	mg	50062	56	
Bonding wire	Other inorganic materials	0.788	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.788	mg	1000000	361	
Encapsulation	Other inorganic materials	526.857	mg	supplier	mold compound	Silica, vitreous	60676-86-0		426.755	mg	810002	196661	
				supplier	mold compound	Phenol resin	9003-35-4		31.611	mg	59999	14567	
				supplier	mold compound	Carbon black	1333-86-4		4.215	mg	8000	1942	
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		53.739	mg	101999	24765	
				supplier	mold compound	Metal hydroxide	21645-51-2		10.537	mg	20000	4856	
Connections coating	Solder	4.209	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.209	mg	1000000	1940	
Subelement	Ceramics / Glass	89.2	mg	supplier	Ceramic isolator	Nickel (Ni)	7440-02-0		1.07	mg	11996	493	
				supplier	Ceramic isolator	Phosphorus (P)	12185-10-3		0.08	mg	897	37	
				supplier	Ceramic isolator	Manganese (Mn)	7439-96-5		3.479	mg	39002	1603	
				supplier	Ceramic isolator	Titanium (Ti)	7440-32-6		0.366	mg	4103	169	
				supplier	Ceramic isolator	Molybdenum oxide	1313-27-5		4.46	mg	50000	2055	
				supplier	Ceramic isolator	Alumina (Al2O3)	1344-28-1		79.745	mg	894002	36749	